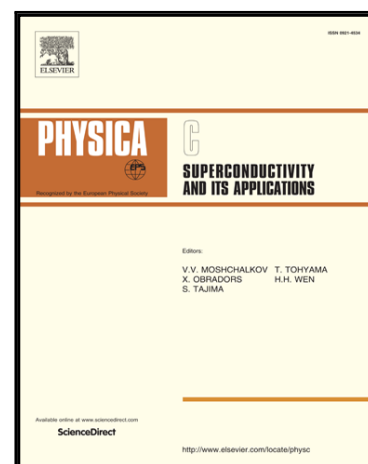


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Study on Reducing the Charge Delay of the No-insulation HTS Coil after Solder Impregnation

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Highlights

- A new impregnation method is proposed for NI coils using conductive material, solder.
- PI control method to reduce the charge delay of the solder impregnated HTS coil.
- The basic theory of the PI control is introduced.
- The experiments and simulations are compared.

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